

Title (en)

LED DIE DISPERSAL IN DISPLAYS AND LIGHT PANELS WITH PRESERVING NEIGHBORING RELATIONSHIP

Title (de)

LED-MATRIXVERTEILUNG BEI ANZEIGEN UND LEUCHTPANEELN MIT ERHALTUNG VON NACHBARSCHAFTSBEZIEHUNGEN

Title (fr)

DISPERSION DE PUCES DE DEL DANS DES DISPOSITIFS D'AFFICHAGE ET PANNEAUX D'ÉCLAIRAGE À PRÉSERVATION DE RELATION DE VOISINAGE

Publication

**EP 2915183 A2 20150909 (EN)**

Application

**EP 13851524 A 20131024**

Priority

- US 201213663519 A 20121030
- US 2013066610 W 20131024

Abstract (en)

[origin: US2014120640A1] A method of dispersing semiconductor chips from a wafer of semiconductor chips onto a substrate while preserving the neighboring relationship of each chip to each adjacent chip is disclosed. The method includes dispersing the wafer into sequential columns of semiconductor chips with a first pitch between columns while preserving the neighboring relationship and sequentially dispersing the columns of semiconductor chips into rows of individual chips with a second pitch between rows onto a substrate while preserving the neighboring relationship.

IPC 8 full level

**H01L 21/00** (2006.01)

CPC (source: EP US)

**H01L 21/67144** (2013.01 - EP US); **H01L 21/67721** (2013.01 - US); **H01L 21/6836** (2013.01 - US); **H01L 21/68757** (2013.01 - US); **H01L 21/68778** (2013.01 - US); **H01L 25/042** (2013.01 - EP US); **H01L 25/0753** (2013.01 - EP US); **H01L 25/50** (2013.01 - US); **H01L 27/1222** (2013.01 - US); **H01L 27/1225** (2013.01 - US); **H01L 31/18** (2013.01 - US); **H01L 33/0095** (2013.01 - EP US); **H01L 33/44** (2013.01 - US); **H01L 33/58** (2013.01 - US); **H01L 33/62** (2013.01 - US); **H01L 2224/83** (2013.01 - EP US); **H01L 2224/95** (2013.01 - EP US); **H01L 2225/06527** (2013.01 - US); **H01L 2225/06555** (2013.01 - US); **H01L 2924/0002** (2013.01 - EP US); **H01L 2933/0025** (2013.01 - US); **H01L 2933/0058** (2013.01 - US); **H01L 2933/0066** (2013.01 - US); **Y10T 29/4913** (2015.01 - US); **Y10T 156/171** (2015.01 - EP US)

Designated contracting state (EPC)

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